

# **ALPHA® EF-6850HF**

Halogen-Free, Low-Solids, Alcohol-Based, No-Clean Wave Soldering Flux

#### **DESCRIPTION**

**ALPHA EF-6850HF** is a halogen-free, low-solids, alcohol-based, no-clean flux for lead-free wave soldering. It is formulated for both standard and thicker, high-density PCBs used in lead-free applications. It is designed for low bridging to provide superior performance in pin testing, hole-fill and solderballing. Additionally, it provides good cosmetics with a uniform, tack-free residue.

READ ENTIRE TECHNICAL DATA SHEET BEFORE USING THIS PRODUCT

## **FEATURES & BENEFITS**

#### Features:

- Halogen-free
- Unique activator / package
- Compliant to GR-78-CORE (Telcordia/Bellcore)
- Low surface tension
- Thermally stable
- Tack-free residue

### Benefits:

- Environmentally friendly. Complies with halogen free industry standards
- Produces highly reliable assemblies with excellent cosmetics and pin testability
- High through hole penetration rate and uniform SMT pad coverage
- Excellent soldering in both single and dual wave processing using SAC305 or other low silver alloys
- Pin testable, uniform, transparent, tack free residue





#### **APPLICATION GUIDELINES**

**Preparation:** In order to maintain consistent soldering performance and electrical reliability, it is important to begin the process with circuit boards and components that meet established requirements for solderability and ionic cleanliness. It is suggested that assemblers establish specifications on these items with their suppliers and that suppliers provide Certificates of Analysis with shipments and/or assemblers perform incoming inspection. A common specification for the ionic cleanliness of incoming boards and components is  $10 \, \mu g/in2 \, maximum$ , as measured by an Omegameter with heated solution.

Care should be taken in handling the circuit boards throughout the process. Boards should always be held at the edges. The use of clean, lint-free gloves is also recommended.

Conveyors, fingers and pallets should be cleaned regularly to reduce the build-up of flux residues. ALPHA AutoClean 40 cleaner is recommended for this process.

**Flux Application:** ALPHA EF-6850HF can be applied by spray, foam or wave application. A uniform coating of flux is essential to successful soldering. When applying flux, it is important to run a series of tests to ensure that the flux is being applied uniformly, that it is penetrating from top to bottom of the board on all holes to be soldered and to make sure that excessive amounts of flux are not being applied.

There are various methods for conducting these tests. Consult with your local Alpha Customer Technical Service Representative for more information.

Operating Parameter	SAC 305 or Low Ag SAC alloys	
Amount of Elux Applied	Single : 1,200 to 1,600 µg/in² solids	
Amount of Flux Applied	Dual :1,400 to 2,000 μg/in² solids	
Top Side Preheat Temperature	90 to 120 °C	
Bottom side Preheat Temperature	110 to 140 °C	
Recommended Preheat Profile	Straight ramp to desired top-side temperature	
Maximum Ramp Rate of Topside Temperature (to avoid component damage)	2 °C/second (35 °F/second) maximum	
Contact Time in the Solder (includes Chip Wave and Primary Wave)	3 to 6 seconds	
Solder Pot Temperature	255 to 265 °C	

These are general guidelines which have proven to yield excellent results; however, depending upon your equipment, components, and circuit boards, your optimal settings may be different. In order to optimize your process, it is recommended to perform a design experiment, optimizing the most important variables (amount of flux applied, conveyor speed, topside preheat temperature, solder pot temperature and board orientation).







**Flux Solids Control:** If rotary drum spray fluxing, the flux solids will need to be controlled via thinner addition. For measuring the solids content, Alpha's Flux Solids Control Kit #3, a digital titrator, is suggested. Request Alpha's Reference Bulletin for details on the kit and titration procedure. When operating a rotary drum fluxer continuously, the acid number should be checked every eight hours. Over time, debris and contaminants will accumulate in recirculating type flux applicators. For consistent soldering performance, dispose of spent flux every 40 hours of operation. After emptying the flux, the reservoir should be thoroughly cleaned with IPA.

**Residue Removal:** ALPHA EF-6850HF is a no-clean flux and the residues are designed to be left on the board. If desired, flux residues can be removed with ALPHA 2110 saponifier cleaner and with other commercially available solvent cleaners and saponifier cleaners.

#### **HALOGEN STATUS**

Standard	Requirement	Test Method	Status
IEC 61249-2-21	Post soldering residues contain <900ppm each or total of <1500ppm Br or CI from flame retardant source	TM EN 14582 Solids extraction	PASS
JEDEC - A Guideline for Defining "Low Halogen" Electronic products	Post soldering residues contain <1000ppm Br or Cl from flame retardant source	per IPC TM 2.3.34	PASS

# **TECHNICAL DATA**

Physical Properties	Typical Values	Parameters/Test Method	Typical Values	
Appearance	Clear, Light Amber	pH, 5% v/v aqueous solution	2.8	
Solids Content, wt/wt	4.0%	Recommended Thinner	ALPHA 425	
Specific Gravity @ 25 °C (77 °F)	0.793	Shelf Life	12 months	
Acid Number (mg KOH/g)	21.47	IPC J-STD-004	ROL0	
Flash Point (T.C.C.)	17 °C	Designation		



# **CORROSION & ELECTRICAL TESTING - SAC305 ALLOY**

# **Corrosion Test**

Test		Requirement for ROL0	Results
	Silver Chromate Paper	No detection of halide	PASS
	IPC-TM 650 Test Method 2.3.33	No detection of fialide	
	Copper Mirror Test	No complete removal of copper	PASS
IPC	IPC-TM 650 Test Method 2.3.32	No complete removal of copper	PASS
	Copper Corrosion Test	No evidence of corrosion	PASS
	IPC-TM650 Test Method 2.6.15	N/A	
JIS	Copper Corrosion Test	No evidence of corrosion	PASS
	JIS Z3197:1999 Test Method 8.4.1	No evidence of corrosion	FASS

## IPC J-STD-004B Surface Insulation Resistance

Test	Requirements (<1.0 x 10 <sup>8</sup> allowed during initial 24 hrs.)	Results (min. of all measurements recorded)		
		< 24 Hrs	24 to 168 Hrs	Visual
"Comb-Down" Un- cleaned	> 1.0 x 10 <sup>8</sup> Ω	6.8 x 10 <sup>10</sup> Ω	6.2 x 10 <sup>10</sup> Ω	PASS
"Comb-Up" Un-cleaned	> 1.0 x 10 <sup>8</sup> Ω	1.4 x 10 <sup>10</sup> Ω	2.7 x 10 <sup>10</sup> Ω	PASS
Control Boards	$> 1.0 \times 10^{9} \Omega$	1.8 x 10 <sup>11</sup> Ω	1.8 x 10 <sup>11</sup> Ω	NA

IPC Test Condition (per J-STD-004B TM2.6.3.7): IPC B-24 coupons, 12V, 40 °C, 90% RH, measurements recorded @ 20min intervals

## JIS Standard Surface Insulation Resistance

Test	Conditions	Requirements	Controls	Results
Initial	Ambient	> 1.0 x 10 <sup>11</sup> Ω	9.7 x 10 <sup>11</sup> Ω	9.8 x 10 <sup>11</sup> Ω
After 7 days	40 °C / 90% RH	> 1.0 x 10 <sup>10</sup> Ω	$1.0 \times 10^{12} \Omega$	7.5 x 10 <sup>11</sup> Ω
Recovered	25 °C/75% RH, 7 days	> 1.0 x 10 <sup>11</sup> Ω	$1.0 \times 10^{12} \Omega$	1.0 x 10 <sup>12</sup> Ω

All Measurements @ 100V, JIS Boards

(0.32mm lines, 0.32 mm spacing, same as IPC B25 Boards).



## **Bellcore Surface Insulation Resistance**

# **Bellcore Electromigration**

Test	SIR (Initial)¹	SIR (Final) <sup>1</sup>	Requirement	Result	Visual Result
"Comb-Up"	1.0 x 10 <sup>11</sup> Ω	3.5 x 10 <sup>11</sup> Ω	SIR (Initial)/SIR (Final) <10	0.29	PASS
Un-cleaned	1.0 X 10 22	3.5 X 1072		0.29	PASS
"Comb-Down"	2.1 x 10 <sup>10</sup> Ω	6.5 x 10 <sup>10</sup> Ω	SIR (Initial)/SIR (Final) <10	0.32	PASS
Un-cleaned	2.1 X 10 ° \( \)2	0.5 X 10 · 12		0.32	PASS
Control	1.0 x 10 <sup>11</sup> Ω	5.9 x 10 <sup>11</sup> Ω	Not applicable	0.17	PASS

Bellcore Test Condition (per GR 78-CORE, Issue 1): 65 °C/85% RH/500 Hours/10V, measurement @ 100V/IPC

B-25B Pattern (12.5 mil lines, 12.5 mil spacing).





#### **SAFETY & WARNING**

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use. **Safety Data Sheets are available at MacdermidAlpha.com/assembly-solutions/knowledge-base.** 

## **CONTACT INFORMATION**

# To confirm this document is the most recent version, please contact Assembly@MacDermidAlpha.com

www.macdermidalpha.com

North America 109 Corporate Blvd. South Plainfield, NJ 07080, USA 1.800.367.5460 **Europe**Unit 2, Genesis Business Park

Albert Drive Woking, Surrey, GU21 5RW, UK 44.01483.758400 Asia

8/F., Paul Y. Centre 51 Hung To Road Kwun Tong, Kowloon, Hong Kong 852.3190.3100

Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE . Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

DISCLAIMER: All statements, technical information and recommendations contained herein are based on tests we believe to be reliable, but the accuracy or completeness thereof is not guaranteed. No statement or recommendation shall constitute a representation unless set forth in an agreement signed by officers of seller and manufacturer. NO WARRANTY OF MERCHANTABILITY, WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE OR ANY IMPLIED WARRANTY IS MADE. The following warranty is made in lieu of such warranties and all other warranties, express, implied, or statutory. Products are warranted to be free from defects in material and workmanship at the time sold. The sole obligation of seller and manufacturer under this warranty shall be to replace any noncompliant product at the time sold. Under no circumstances shall manufacturer or seller be liable for any loss, damage or expense, direct, incidental or consequential, arising out of the inability to use the product. Notwithstanding the foregoing, if products are supplied in response to a customer request that specifies operating parameters beyond those stated above, or if products are used under conditions exceeding said parameters, the customer by acceptance or use thereof assumes all risk of product failure and of all direct, indirect, incidental and consequential damages that may result from use of the products under such conditions, and agrees to exonerate, indemnify, defend and hold harmless MacDermid, Incorporated and its affiliates therefrom. No suggestion for product use nor anything contained herein shall be construed as a recommendation to use any product in a manner that infringes any patent or other intellectual property rights, and seller and manufacturer assume no responsibility or liability for any such infringement.

© 2019 MacDermid, Inc. and its group of companies. All rights reserved. "(R)" and "TM" are registered trademarks or trademarks of MacDermid, Inc. and its group of companies in the United States and/or other countries.

